

ABSTRACT OF THE DISCLOSURE

A chip scale package (CSP) structure for an image sensor includes a semi-conductor image sense chip and multiple bonding pads formed on a top face of the semi-conductor image sense chip. A
5 conducting wire extends from each of the multiple bonding pads by wire-bonding. Liquefied jelly-like material is covered with the top face of the semi-conductor image sense chip and forming a transparent layer on the top face of the semi-conductor image sense chip after drying up. The transparent layer has a thickness being equal to a height of each of
10 the conduct wire relative to the top face of the semi-conductor image sense chip.